

## -30V P-Channel Enhancement Mode MOSFET

**V**<sub>DS</sub>= -30V

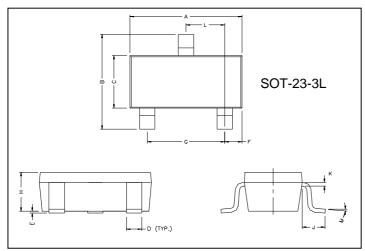
 $R_{DS(ON)},~V_{gs}@\mbox{-}10V,~I_{ds}@\mbox{-}4.2A<64m~\Omega$ 

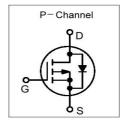
 $R_{DS(ON)}$ ,  $V_{gs}$ @-4.5V,  $I_{ds}$ @-4.0A < 75m  $\Omega$ 

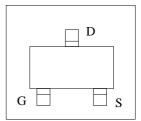
 $R_{DS(ON)},~V_{gs}@\mbox{-}2.5V,~I_{ds}@\mbox{-}1.0A<\mbox{120m}~\Omega$ 

#### **Features**

Advanced trench process technology High Density Cell Design For Ultra Low On-Resistance Package Dimensions







REF.	Millimeter		REF.	Millimete		
	Min.	Max.	NEI.	Min.	Max.	
Α	2.70	3.10	G	1.90 REF.		
В	2.65	2.95	Н	1.00	1.30	
C	1.50	1.70	K	0.10	0.20	
D	0.35	0.50	7	0.40	-	
Е	0	0.10	L	0.85	1.15	
F	0.45	0.55	М	0°	10°	

### Maximum Ratings and Thermal Characteristics (TA = 25oC unless otherwise noted)

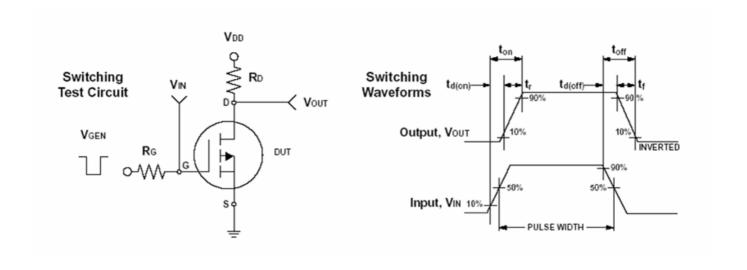
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	-30	V		
Gate-Source Voltage	V <sub>GS</sub>	±12			
Continuous Drain Current	I <sub>D</sub>	-4.2	Α		
Pulsed Drain Current	I <sub>DM</sub>	-30			
Marianum Davias Dissination	$TA = 25^{\circ}C$	- P <sub>D</sub>	1.4	W	
Maximum Power Dissipation	$TA = 75^{\circ}C$		1		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C		
Junction-to-Ambient Thermal Resistance (PCB mounted)	$R_{\theta JA}$	125	°C/W		



# ELECTRICAL CHARACTERISTICS (TA = 25oC unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Тур.	Miax.	Unit
Static			•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$V_{GS} = 0V, I_D = -250uA$	-30			V
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = -10V, I_D = -4.2A$		42.0	64.0	mΩ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = -4.5V, I_D = -4A$		64.0	75.0	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -2.5V, I <sub>D</sub> =-1A		80.0	120.0	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250uA$	$V_{DS} = V_{GS}, I_{D} = -250uA$ -0.7		-1.3	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -24V, V <sub>GS</sub> = 0V			-1	uA
Gate Body Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	nA
Forward Transconductance	<b>G</b> fs	$V_{DS} = -5V, I_{D} = -5A$	7	11	_	S
Dynamic	<u>.</u>					
Total Gate Charge	Qg	$V_{DS} = 20V, I_D = 5.7A$		9.4		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 20V, I_D = 5.7A$ $V_{GS} = 10V$		2		
Gate-Drain Charge	Q <sub>gd</sub>	VGS = 10V		3		
Turn-On Delay Time	n Delay Time t <sub>d(on)</sub>			6.3		
Turn-On Rise Time	tr	$V_{DD} = 20V$ , $RL=20\Omega$		3.2		ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = 1A$ , $V_{GEN} = 10V$ $R_G = 6\Omega$		38.2		
Turn-Off Fall Time	t <sub>f</sub>	$K_G = 022$		12		
Input Capacitance	C <sub>iss</sub>	\/ 0\/ \/ 0\/		954		pF
Output Capacitance	Coss	$V_{DS} = 8V$ , $V_{GS} = 0V$		115		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0 MHz		77		
Source-Drain Diode	· · · · · · · · · · · · · · · · · · ·		•	•		
Max. Diode Forward Current	Is				-2.2	Α
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.8A, V <sub>GS</sub> = 0V			-1.0	V

Note: Pulse test: pulse width <= 300us, duty cycle<= 2%



## Typical Characteristics (TJ =25℃ Noted)

